

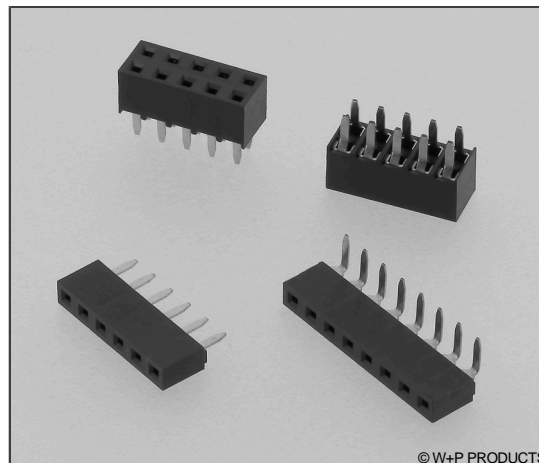
46-342 Economy Version

Buchsenleisten RM 2,54mm - BH 5mm

Female Headers, 2.54mm Pitch - 5mm Profile

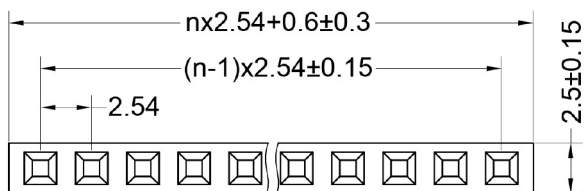
Technische Daten / Technical Data

Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	Thermoplastic, rated UL94 V-0
Kontaktmaterial	Kupferlegierung
Contact Material	Copper alloy
Kontaktfläche	Au über Ni
Contact Surface	Au over Ni
Durchgangswiderstand	< 20 mΩ
Contact Resistance	< 20 mΩ
Isolationswiderstand	> 1000 MΩ
Insulation Resistance	> 1000 MΩ
Spannungsfestigkeit	1000 V AC
Test Voltage	1000 V AC
Nennstrom	3 A
Current Rating	3 A
Temperaturbereich	-40 °C ~ +105 °C
Temperature Range	-40 °C ~ +105 °C
Verarbeitung	260 °C für 10 sec. / 230 °C für 30-60 sec.
Processing	260 °C for 10 sec. / 230 °C for 30-60 sec.

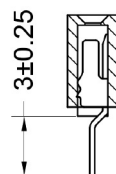
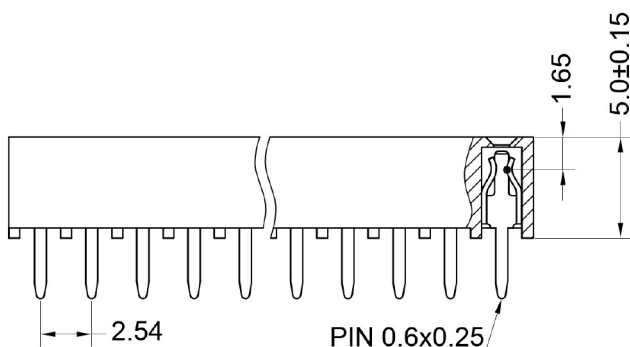
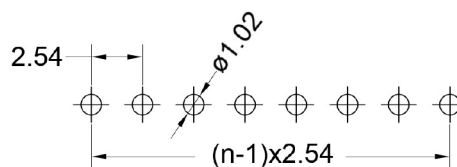


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Geeignet für 0,635mm Vierkantstifte
Mates with 0.635mm square pins



Recommended PCB Layout (Top Side)
(PCB BOARD TOLERANCE ± 0.05)



Series

46-342

Contacts*

08

02-40 Einreihig
Single row

Type

1

1 Einreihig, gerade
Single row, straight

Plating

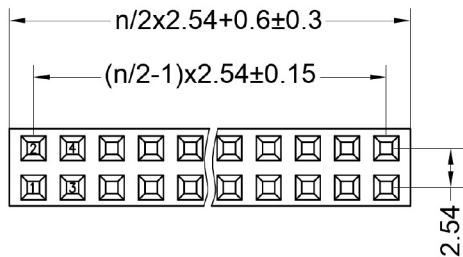
00

00 Vergoldet
Gold plated

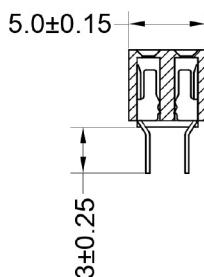
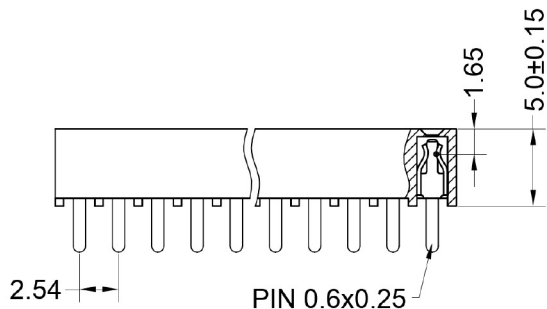
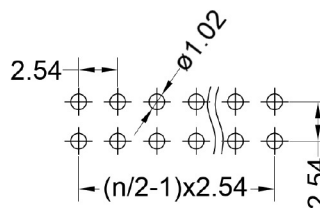
46-342 Economy Version

Buchsenleisten RM 2,54mm - BH 5mm

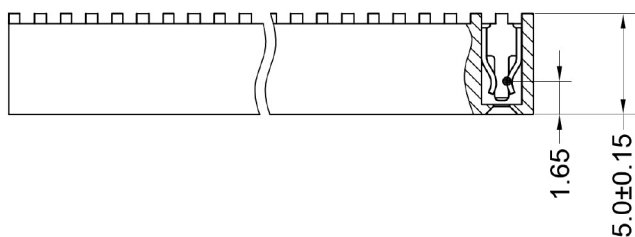
Female Headers, 2.54mm Pitch - 5mm Profile



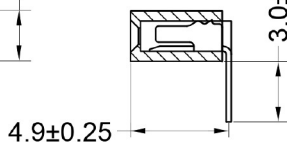
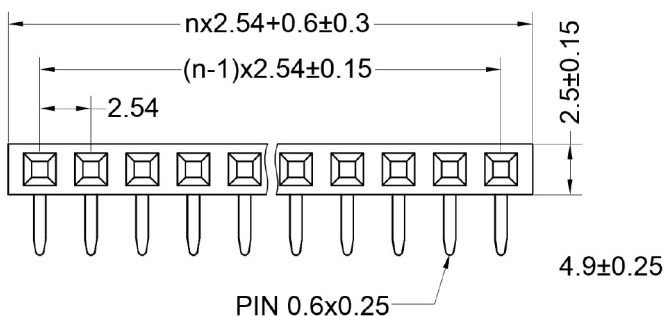
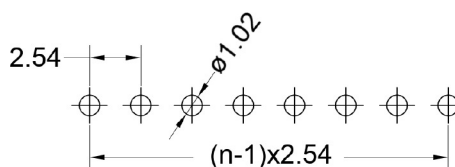
Recommended PCB Layout (Top Side)
(PCB BOARD TOLERANCE ±0.05)



Series	Contacts *	Type	Plating
46-342	12 04-60 Zweireihig Double row	2 2 Zweireihig, gerade Double row, straight	00 00 Vergoldet Gold plated



Recommended PCB Layout (Top Side)
(PCB BOARD TOLERANCE ±0.05)



Series	Contacts *	Type	Plating
46-342	10 02-40 Einreihig Single row	3 3 Einreihig, gewinkelt Single row, right-angled	00 00 Vergoldet Gold plated

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** -
please replace by your specifications.

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	untere Temperaturangabe [°C]
Verweildauer oberhalb T_L	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	Lower Temperature [°C]
Duration above T_L	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

